1734261-3 PENDING OBSOLESCENCE

TE Internal #: 1734261-3

TE Internal Description: 1.25 WTB, HDR, SMT, RA, 3P

AMP HPI 1.25 mm Headers

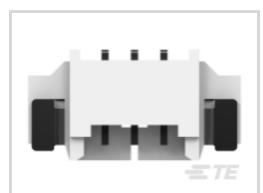
View on TE.com >



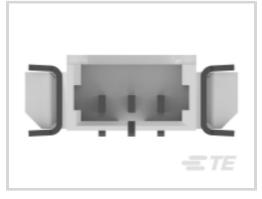
Connectors > PCB Connectors > PCB Headers & Receptacles > AMP HPI 1.25 mm Headers











Connector System: Wire-to-Board

Number of Positions: 3

Number of Rows: 1

Centerline (Pitch): 1.25 mm [.049 in]
PCB Mount Orientation: Right Angle

All AMP HPI 1.25 mm Headers (1)

Features

Product Type Features

| Connector System | Wire-to-Board |
|-----------------------------------|-----------------------|
| Header Type | Partially Shrouded |
| Sealable | No |
| Connector & Contact Terminates To | Printed Circuit Board |
| PCB Connector Assembly Type | PCB Mount Header |

Configuration Features

| Connector Contact Load Condition | Fully Loaded |
|----------------------------------|--------------|
| Number of Positions | 3 |
| Number of Rows | 1 |
| PCB Mount Orientation | Right Angle |

Electrical Characteristics

| Operating Voltage | 100 VAC |
|-------------------|---------|
| | |

Body Features



| Primary Product Color | Natural |
|---|--------------------------------|
| Contact Features | |
| PCB Contact Termination Area Plating Material Thickness | 2.54 μm[100 μin] |
| Contact Layout | Inline |
| Mating Tab Width | .74 mm[.029 in] |
| Mating Tab Thickness | .3 mm[.012 in] |
| Contact Mating Area Plating Material Thickness | 2.54 μm[100 μin] |
| PCB Contact Termination Area Plating Material Finish | Matte |
| Contact Mating Area Plating Material Finish | Matte |
| PCB Contact Termination Area Plating Material | Tin |
| Contact Base Material | Phosphor Bronze |
| Contact Mating Area Plating Material | Nickel |
| Contact Type | Pin |
| Contact Current Rating (Max) | 1 A |
| Termination Features | |
| Rectangular Termination Post & Tail Thickness | .3 mm[.012 in] |
| Terminations per Post (Max) | 3 |
| Rectangular Termination Post & Tail Width | .35 mm[.014 in] |
| Termination Method to Printed Circuit Board | Surface Mount |
| Mechanical Attachment | |
| Mating Alignment Type | Polarization |
| Mating Retention | Without |
| PCB Mount Retention Type | Solder Peg |
| Connector Mounting Type | Board Mount |
| Mating Alignment | With |
| PCB Mount Alignment | Without |
| PCB Mount Retention | With |
| Housing Features | |
| Housing Material | High Temperature Thermoplastic |
| Centerline (Pitch) | 1.25 mm[.049 in] |
| Dimensions | |
| Connector Length | 9.04 mm[.355 in] |
| | |



| Connector Height | 3.45 mm[.136 in] |
|-----------------------------|---------------------------|
| Connector Width | 4.7 mm[.185 in] |
| Usage Conditions | |
| Operating Temperature Range | -40 - 85 °C[-40 - 185 °F] |
| Operation/Application | |
| Circuit Application | Signal |
| Industry Standards | |
| UL Flammability Rating | UL 94V-0 |
| Packaging Features | |
| Packaging Quantity | 1000 |
| Packaging Type | Reel |

Product Compliance

For compliance documentation, visit the product page on TE.com>

| EU RoHS Directive 2011/65/EU | Compliant |
|---|---|
| EU ELV Directive 2000/53/EC | Compliant |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC |
| Halogen Content | Not Low Halogen - contains Br or Cl > 900 ppm. |
| Solder Process Capability | Reflow solder capable to 260°C |

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach



Compatible Parts









Customers Also Bought



















Documents

Product Drawings
1.25 WTB, HDR, SMT, RA, 3P

English

CAD Files

Customer View Model ENG_CVM_1734261-3_A.3d_igs.zip

English



Customer View Model

ENG_CVM_1734261-3_A.3d_stp.zip

English

Customer View Model

ENG_CVM_1734261-3_A.2d_dxf.zip

English

3D PDF

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages

HPI Connectors QRG

English

Product Specifications

Application Specification

English

Product Environmental Compliance

Product Compliance Document

English

Product Compliance Document

English